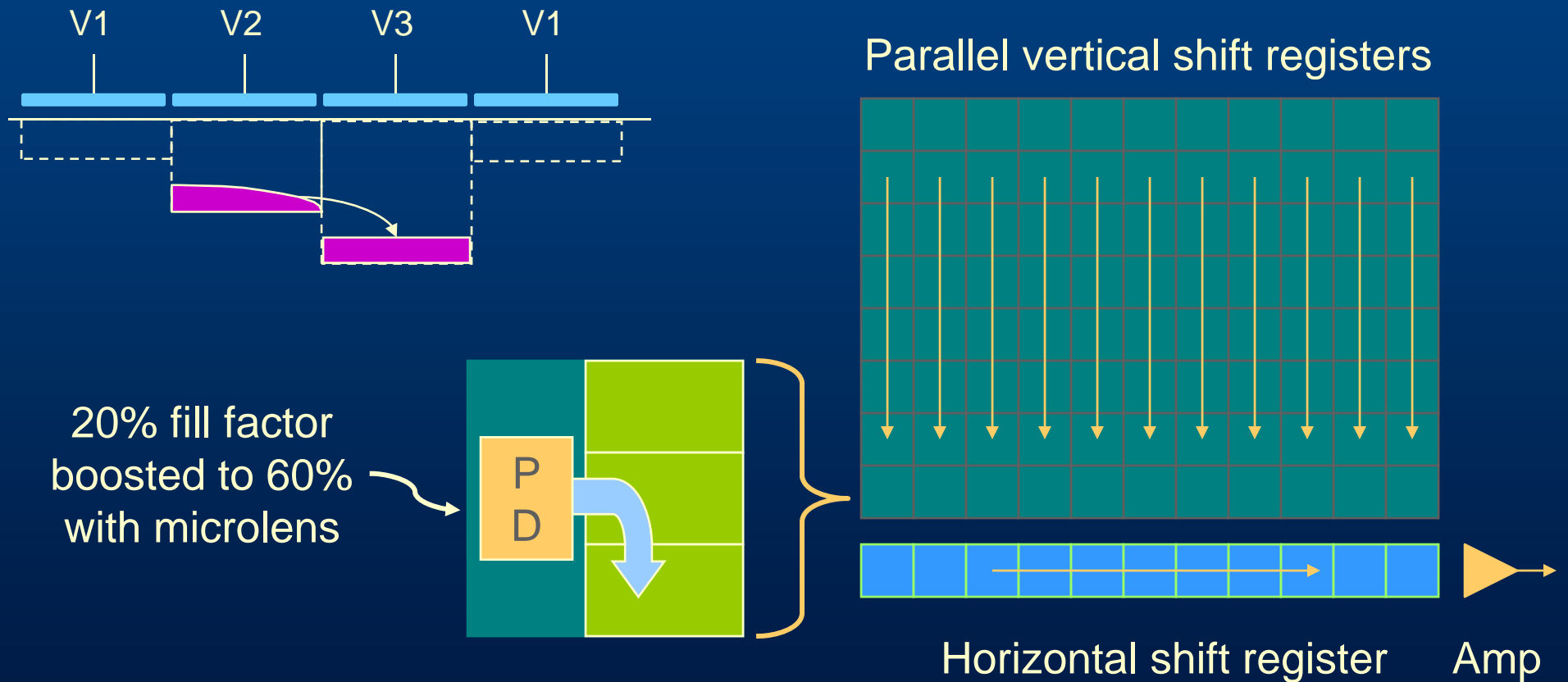


CHARGE-COUPLED DEVICES (CCDs)



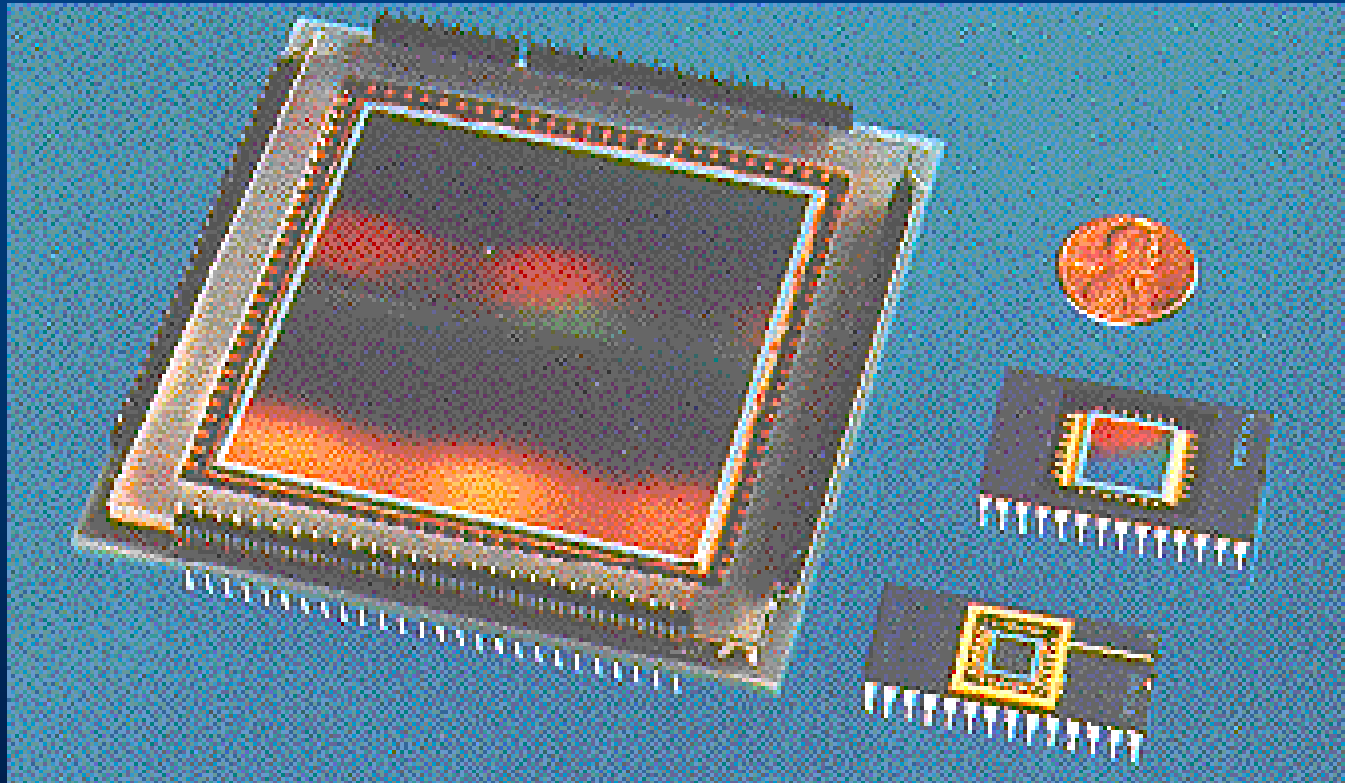
- Charge-coupled devices shift charge one step at a time to a common output amplifier





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CCDS Are a Mature Technology



- DALSA 25 Mpixel sensor



- Fabrication process tailored for high quantum efficiency
- All charge readout through a single amplifier so no fixed pattern noise (offsets).
- Ability to add charge in charge domain without noise good for some signal processing (e.g. time-delay-integration or TDI scanners).
- Incumbent technology (over 30 years of development)

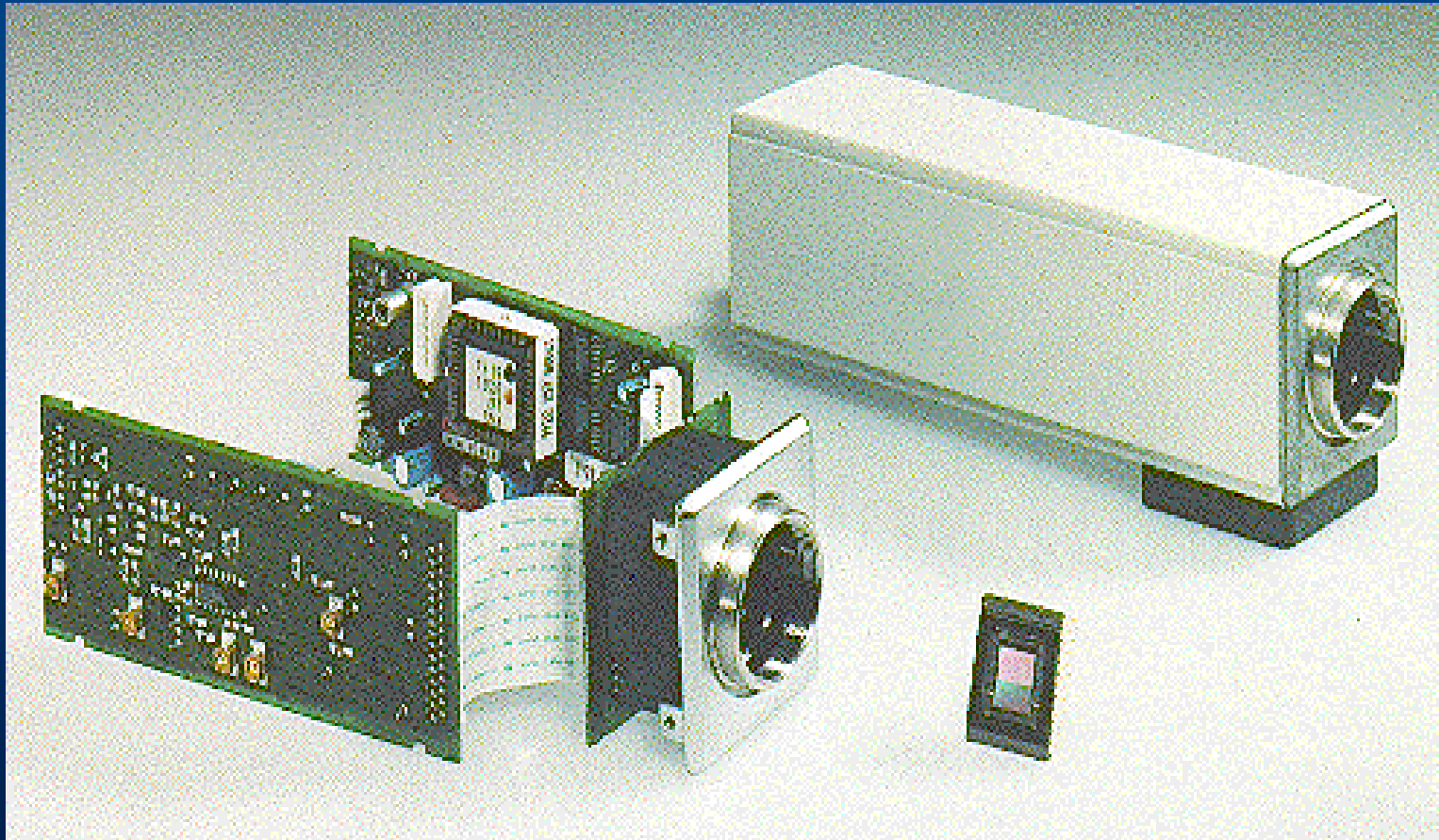


- Requires high charge transfer efficiency
 - Special fabrication process adds cost
 - Larger voltage swings, different voltage levels
- Difficult to integrate on-chip timing, control, drive and signal chain electronics
 - Process integration increases cost, reduces yield
 - Large capacitances require high current levels
- Requires timing generator chip, driver chips, signal processor, ADC and interface chips
- System power in 0.5-2 Watt range
- Architecture yields serial access to image data



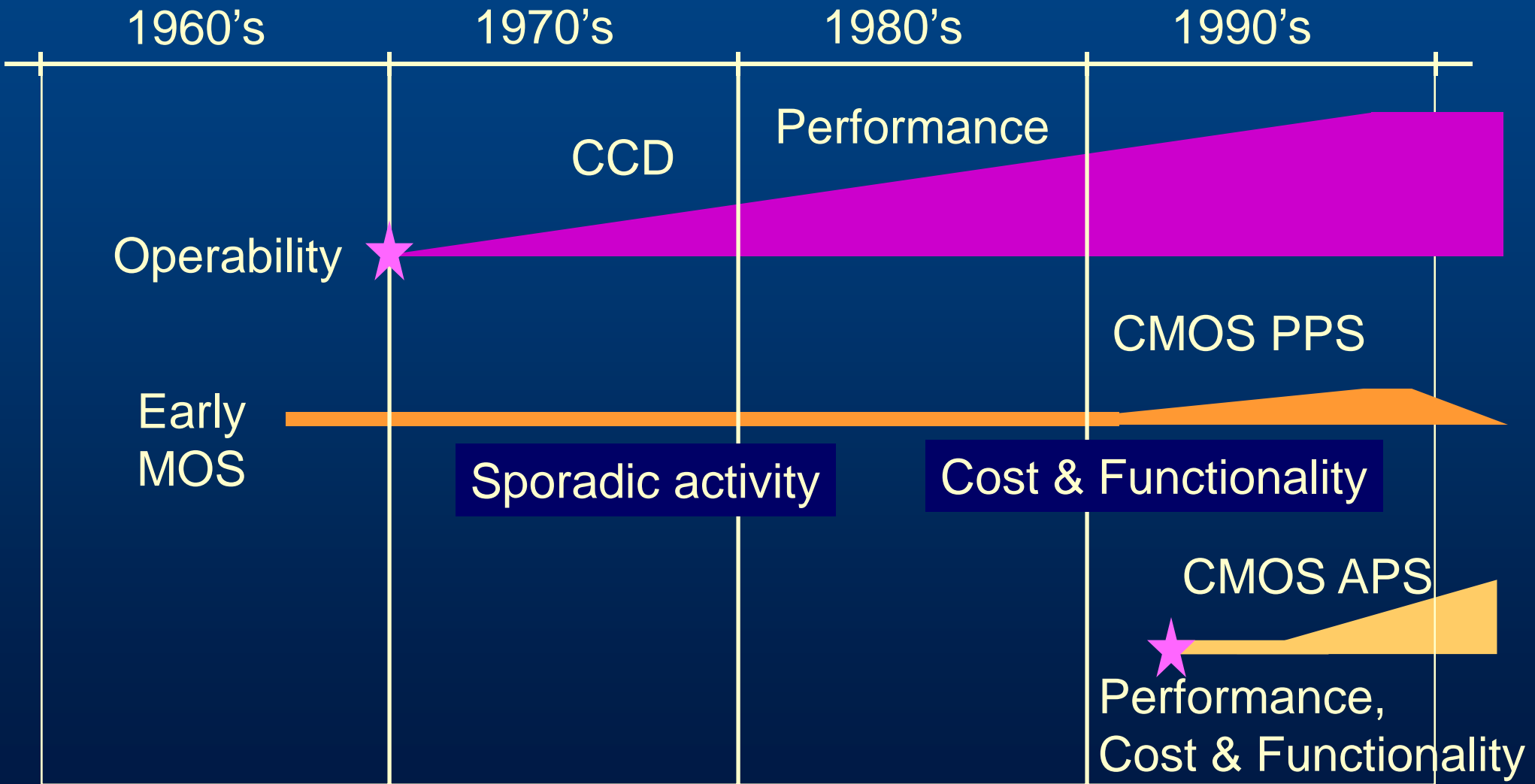
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Total CCD Camera Power is High



- CCD imaging systems require many off-chip components

CMOS IMAGE SENSOR HISTORY

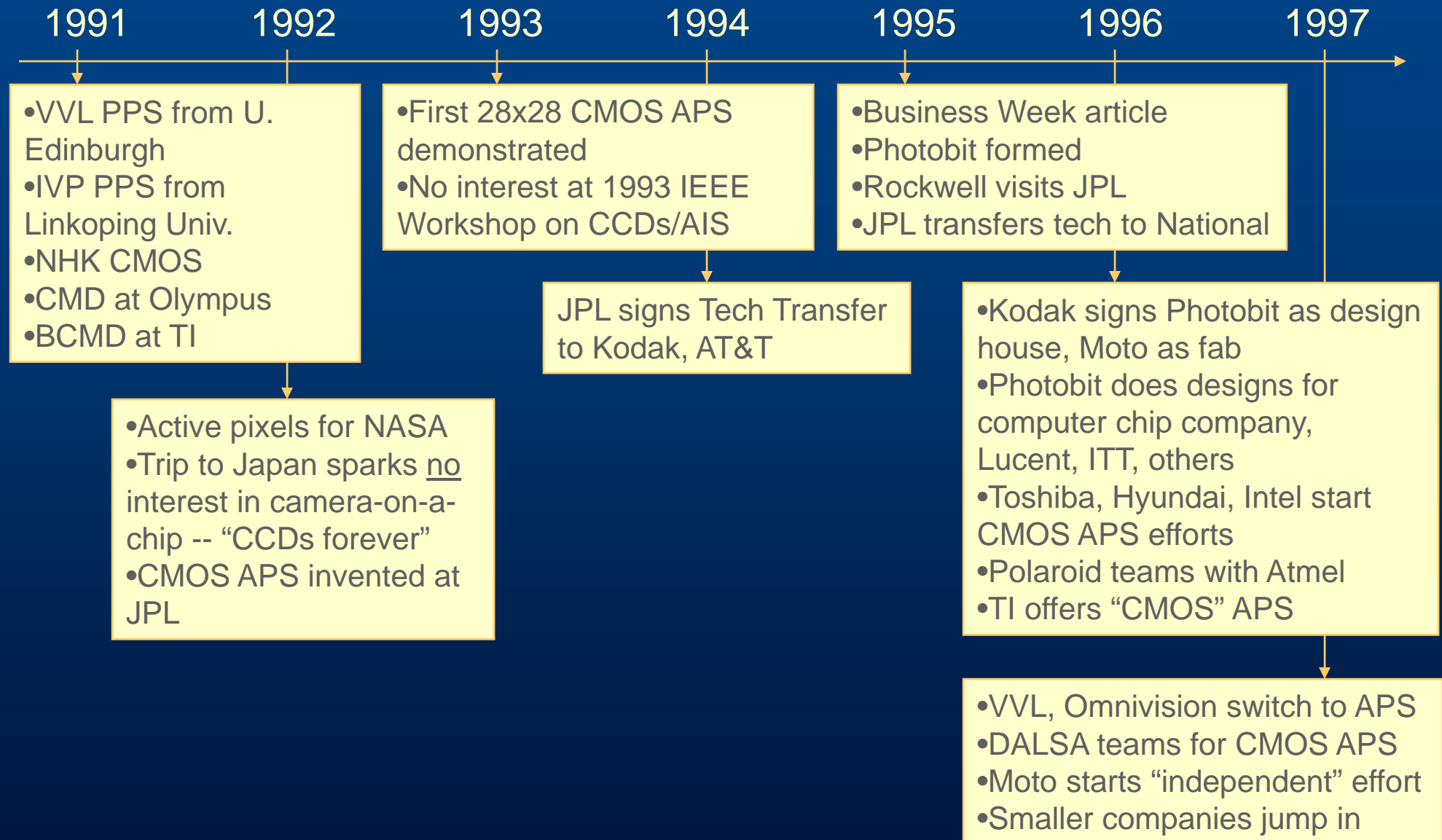




- 1960's Early work on MOS imaging devices
 - *They don't work too well due to state of the art of MOS*
- 1970's CCDs work better than MOS devices
- 1980's Limited work on MOS/CCD imagers
- 1990's CMOS passive pixels commercialized, low performance
- 1993 First CMOS APS demonstrated (28x28) by JPL
- 1994 CMOS APS performance comparable to CCDs
- 1995 CMOS APS as large as 1Kx1K demonstrated
 - *Photobit formed by JPL team to commercialize CMOS APS*
- 1996 Photobit demonstrates high performance CMOS APS with on-chip ADC at video rates
- 1997 Photobit reports world's first high performance digital camera-on-a-chip (Stanford Hot Chips Symposium)



Technology Acceptance





- CMOS state of the art is ripe for image sensors
 - Design rules permit competitive pixel sizes
 - Defects and contamination well controlled
 - Threshold voltages stable and fairly uniform
 - And now foundries offer specialized image sensor modules
- Customers demand low power, miniaturized systems-on-a-chip
- Circuit techniques developed for high performance
 - Active pixel provides gain in pixel and lower noise
 - Use of double-correlated sampling and double-delta sampling on-chip removes temporal & fixed pattern noise
 - Column parallel architecture permits low analog bandwidths to reduce noise and artifacts and maintain high frame rate.
 - Low power imaging circuit techniques reduce power to mW levels



- *CMOS Camera-on-a-chip technology is better than CCDs because:*
 - Much lower power - important for portable applications
 - System-on-a-chip integration allows smaller cameras
 - Lower cost of sensor chip and fewer components in camera
 - Easy digital interface for faster camera design & time to market
 - Less image artifacts - no blooming or smear, with same sensitivity
 - Higher dynamic range for security and auto applications
 - Digital output for faster readout speeds and frame rates
 - Direct addressing of pixels allows electronic pan/tilt/zoom
 - Faster design cycles means faster evolution path